

Title (en)

Apparatus for and method of polishing workpiece

Title (de)

Verfahren und Vorrichtung zum Polieren von Werkstücken

Title (fr)

Procédé et dispositif pour le polissage de pièces

Publication

EP 1151824 A1 20011107 (EN)

Application

EP 01115108 A 19961009

Priority

- EP 96116166 A 19961009
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- JP 17173596 A 19960611

Abstract (en)

A polishing apparatus for polishing a workpiece such as a semiconductor wafer has a turntable with an abrasive cloth mounted on an upper surface thereof, and a top ring for holding a workpiece and pressing the workpiece against the abrasive cloth under a first pressing force to polish the workpiece. The top ring has a recess defined therein for accommodating the workpiece therein. A presser ring is vertically movably disposed around the top ring, and pressed against the abrasive cloth under a variable second pressing force. The first and second pressing forces are variable independently of each other, and the second pressing force is determined based on the first pressing force.

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IPC 8 full level

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CPC (source: EP KR US)

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Citation (search report)

- [XA] EP 0548846 A1 19930630 - CYBEQ SYSTEMS [US]
- [E] EP 0747167 A2 19961211 - APPLIED MATERIALS INC [US]
- [E] US 5584751 A 19961217 - KOBAYASHI HIROYUKI [JP], et al
- [A] PATENT ABSTRACTS OF JAPAN vol. 006, no. 089 (M - 132) 27 May 1982 (1982-05-27)

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DE FR

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